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(71)Applicant: SONY CORP

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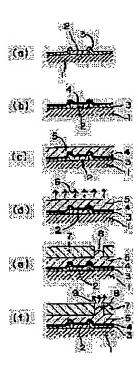
(72)Inventor: ITOU MUTSUSADA

(54) FORMATION OF BUMP ON SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To allow formation of good bumps for all devices by coating an underlying material with a photosensitive liquid resist and then laminating a photosensitive dry film resist thereon.

CONSTITUTION: An underlying material, i.e., a barrier metal 4, is formed on a semiconductor wafer 1 provided with an Al pad 2 and a passivation film 3. The barrier metal 4 is then spin coated with a photosensitive liquid resist 5 with a thickness corresponding to the height of the bump and then it is heated and temporarily dried until 49-90% of solvent is gasified 6. Subsequently, photosensitive dry film resist 7 having uniform thickness is applied to the temporarily dried fluid resist 5 and laminated by thermocompression such that the surface of the photosensitive liquid resist 5 is planarized uniformly. Crowns existing on the periphery of the semiconductor wafer 1 are pushed into holes 8 along with excess resist through the thermocompression thus bringing about uniform total thickness over the entire surface of resist 5.



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